**Product End-of-Life Disassembly Instructions**

**Product Category:** Monitors and Displays

**Marketing Name / Model:** HP 22x Display
[List multiple models if applicable.]

- HP 22x 21.5-inch Display
- HP 22x Display
- HP 22x
- HSD-0041-V

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

**NOTE:** Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Main Board<em>1, Power Board</em>1, Key pad Board*1,</td>
<td>3</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by <em>(check all that apply with an “x” inside the “[ ]”):</em> [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain ______</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps panel*1</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>0</td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>0</td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>0</td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord<em>1, HDMI cable</em>1</td>
<td>2</td>
</tr>
</tbody>
</table>

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Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
Gas Discharge Lamps | All are inside monitor carton box | 0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | 0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0
Components and waste containing asbestos | 0
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
--- | --- |
Cross screwdriver | 1 |
Hexagon screwdriver | 1 |
Opening plastic picks | 1 |

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. **Push the button of hinge and stand to unlock the hinge and stand, then pull out the parts form the monitor head.**
2. Loosen 2 screws at the bottom side of the rear cover. Use tool to open the latches and remove the rear cover.
3. Slightly move-up the hook then remove K/B board from rear cover (bottom-left side). Open the switch and remove the K/B cable.
4. Remove the adhesive tapes on the shielding case and unlock the LED cable and LVDS cable from panel side.
5. Disconnect FFC*1 from the interface board.
6. Pull out the control board and privacy board from the mid frame by hand.
7. Remove 3pcs screws to separate the mother board from the shielding case.
8. Remove Key pad board cable LVDS cable speaker cable power board cable from the mother board.
9. Remove screws *5 on the power board and interface board.
10. Disconnect the wire to separate power board and interface board.

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EL-MF877-00
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3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Push the button of hinge and stand to unlock the hinge and stand, then pull out the parts form the monitor head.

2. Loosen 2 screws at the bottom side of the rear cover. Use tool to open the latches and remove the rear cover.

3. Slightly move-up the hook then remove K/B board from rear cover (bottom-left side). Open the switch and remove the K/B cable.
4. Remove the adhesive tapes on the shielding case and unlock the LED cable and LVDS cable from panel side.

5. Disconnect FFC*1 from the interface board.

6. Pull out the control board and privacy board from the mid frame by hand.

7. Remove 3pcs screws to separate the mother board from the shielding case.
8. Remove Key pad board cable LVDS cable speaker cable power board cable from the mother board.

9. Remove screws *5 on the power board and interface board.

10. Disconnect the wire to separate power board and interface board.